

Visegrad Fund
Visegrad Grant No. 21730020
<http://vinmes.eu/>
Visegrad Network

**V4 Seminars for Young Scientists on Publishing Techniques
in the Field of Engineering Science**

How to prepare a paper for final format

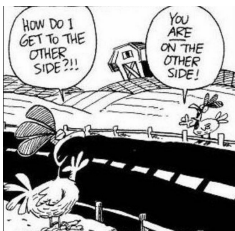
David Bušek
Czech Technical University in Prague

11.6.2018 Slide 1 of 42

Visegrad Fund
Journals article formatting
Visegrad Network

The scientific format may **seem confusing** for the young scientist as every journal has its own requirements

Misunderstanding? → Look out for others, how they do it!




A cartoon showing a person on a bridge looking down at a river. A speech bubble says 'HOW DO I GET TO THE OTHER SIDE?!!'. Another person is on the other side of the river, and a speech bubble says 'YOU ARE ON THE OTHER SIDE!'.

11.6.2018 Slide 2 of 42

Visegrad Fund
Before submission
Visegrad Network

- Do a proper research
- Read the author instructions and format your article according to specific journal requirements




A cartoon showing a person sitting at a desk with a computer, looking at a document. A speech bubble says 'I already wrote the paper. That's why it's so hard to get the right data.'


11.6.2018 Slide 3 of 42

Visegrad Fund

Why is manuscript formatting important?



- Time to publication may be shortened with correct formatting
- Manuscripts that do not meet journal formatting requirements, particularly with respect to title page information, abstract structure, and reference style **are often sent back to the author without review, up to several weeks after the manuscript was first submitted.**




11.6.2018


Slide 4 of 42

Visegrad Fund

Requirement for formats of article journals



- Each academic journal has a specific requirement and its own style of formatting:
 - **Title** (various capitalization methods)
 - **Authors** (abbreviating)
 - **texts**
 - **figures** (and their referencing)
 - **tables** (and their referencing)
 - **references**




11.6.2018


Slide 5 of 42

Visegrad Fund

Journal formatting requirements




- The requirements for how the manuscript should be formatted for the review process may be different from the format of published articles.




11.6.2018

Slide 6 of 42

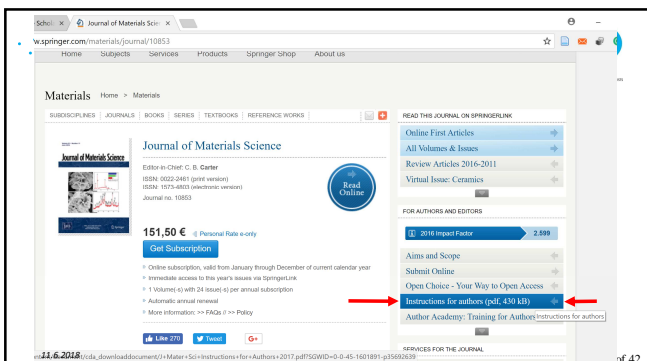


Formatting



- Ensure the format of manuscript is in accordance with the author's guidelines of the journal.
- Ensure the desired line spacing and margin of the journal.
- Arrange texts, paragraphs and figures within a specified margin and position.
- Ensure that references are presented in correct style
- Use the **TEMPLATE** of the journal (if available) for the working document to ensure correct formatting according to the journal standard.

11.6.2018
Slide 7 of 42



Journal of Materials Science

Editor-in-Chief: G. B. Carter
 (ISSN: 0022-2461 (print version)
 (ISSN: 1573-4803 (electronic version)
 Journal no. 10853)

151,50 € | Personal Rate e-only
[Get Subscription](#)

Online subscription, valid from January through December of current calendar year
 Immediate access to this year's issues via SpringerLink
 1 Volume(s) with 24 issue(s) per annual subscription
 Automatic email renewal
 More information: >> FAQs >> Policy

READ THIS JOURNAL ON SPRINGERLINK


Online First Articles
 All Volumes & Issues
 Review Articles 2016-2011
 Virtual Issue: Ceramics

FOR AUTHORS AND EDITORS


2016 Impact Factor 2.99
 Aims and Scope
 Submit Online
 Open Choice - Your Way to Open Access
Instructions for authors (pdf, 430 kB)
 Author Academy: Training for Authors (instructions for authors)

SERVICES FOR THE JOURNAL

11.6.2018 of 42



Text



Text formatting

Manuscripts should be submitted in Microsoft Word. PDF is not an acceptable format.

- Use a normal, plain font (e.g., 12-point Times Roman) for text.
- Use only one column.
- Use 1.5 or double-spaced text.
- Use italics for emphasis.
- Use the automatic page numbering function to number the pages.
- Do not use field functions.
- Use tab stops or other commands for indents, not the space bar.
- Use the table function, not spreadsheets, to make tables.
- Use the equation editor or MathType for equations (not the formula editor in Microsoft Word versions).
- Save your file in docx format (Word 2007 or later) or doc (for older Word versions).

Manuscripts with mathematical content should be saved as LaTeX files.

- A LaTeX macro package for authors is available for download. Full instructions on preparing a TeX submission for our editorial management system are available on the [Editorial Manager site](#).

Headings

No more than three levels of displayed headings should be used.

Abbreviations

Abbreviations should be defined at the point of first use and be used consistently thereafter. Abbreviations defined in the abstract should be redefined in the main body of the submission.

Footnotes



Footnotes can be used to give additional information, which may include the citation of a reference included in the reference list. They should not consist solely of a reference citation, and they should

THIS IS ONLY AN EXTRACT

11.6.2018
Slide 9 of 42

Visegrad Fund

Examples of different formats

Formatting requirements

There are no strict formatting requirements but all manuscripts must contain the essential elements needed to convey your manuscript, for example Abstract, Keywords, Introduction, Materials and Methods, Results, Conclusions, Artwork and Tables with Captions.

If your article includes any Videos and/or other Supplementary material, this should be included in your initial submission for peer review purposes.

Divide the article into clearly defined sections.


Figures and tables embedded in text

Please ensure the figures and the tables included in the single file are placed next to the relevant text in the manuscript, rather than at the bottom or the top of the file. The corresponding caption should be placed directly below the figure or table.

11.6.2018 Slide 10 of 42

Visegrad Fund

Unknown formatting

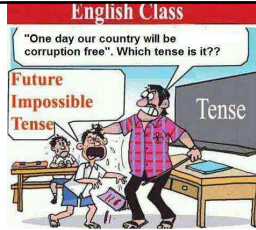


- **The journal guidelines don't include any instructions regarding font, line spacing, margins, or other layout issues. How should I format the text of my paper?**
- **Consistency and simplicity are essential.** The font should be easy to read, and the layout should be consistent throughout the paper. Times New Roman size 12 font, double line spacing, 1-inch margins, and half-inch indentations at the beginning of each paragraph (using the tab key, **not the space bar**) are widely accepted standards.

11.6.2018 Slide 11 of 42

Visegrad Fund

Language control



- Manuscripts should be proof-read and have English language errors corrected before submission as the editor may have to return papers due to poor language usage
- Check misprints, use proofing tools
- If English is not your native language you may want to have your manuscript edited by a **native speaker** or use a **professional language editing service**, where editors will improve the English to ensure that your meaning is clear and identify problems that require your review.
- **YOU ARE THE LAST READER!**

11.6.2018 Slide 12 of 42

Abstract

Previous studies have reported that selective serotonin reuptake inhibitors (SSRIs) may induce or exacerbate rapid eye movement (REM) sleep without atonia (RSWA) and increase the risk of developing REM sleep behavior disorder (RBD). However, most of these studies were retrospective and cross-sectional. *to better guide small sample sizes, and they included data on a mixture of SSRIs.*

Because different SSRIs have different pharmacological profiles, the specific effects of individual SSRIs on RSWA should be studied. In an 8-week, open-label trial of sertraline in depressed patients (n=33), patients were administered 50 mg of sertraline at 8 am on the 1st day, *this dose was* subsequently titrated up to a maximum of 200 mg/day. All patients *underwent* repeated video-polysomnography (VPSG) (at baseline and on days 1, 14, 28, and 56). Both tonic (submental) and phasic (submental and anterior tibialis) RSWA were visually *assessed*; tonic RSWA increased from 3.2±1.8% at baseline to 5.1±2.5% on the 1st day on sertraline and to 10.4±2.7% on the 14th day. *As this value then remained stable until the 36th day.* A similar profile was observed for phasic RSWA in *all* as for the proportion of patients with abnormal phasic anterior tibialis (AT) RSWA. No RBD was observed. The increase in tonic muscle tone during REM sleep over time *was* correlated with reduced REM sleep *percentage* ($p=0.56$, $p=0.004$), PLMI ($r=-0.39$, $p=0.047$), and improvement in depression (ORSD score, $r=-0.43$, $p=0.03$). The increase in phasic submental ($r=-0.53$, $p=0.02$) and anterior

11.6.2018

Slide 16 of 42

Editing service

- Using an editing service is neither a requirement nor a guarantee of acceptance for publication

11.6.2018

Slide 17 of 42

Manuscript submission

Home > Journals > Microelectronics Reliability

Microelectronics Reliability

> Supports Open Access
Editor-in-Chief: Dr. M. Tahoori
> View Editorial Board

ISSN: 0026-2714

Submit Your Paper
View Articles
Guide for Authors

Microelectronics Reliability is dedicated to disseminating the latest research results and related information on the reliability of microelectronic devices, circuits and systems, from materials, process and manufacturing, to design, testing and operation. The coverage of the journal includes the following...

Read more


Most Downloaded Recent Articles Most Cited Open Access Articles

11.6.2018

Slide 18 of 42

Visegrad Fund

References



Visegrad Network

- **Definition:** Reference is a relation between objects in which one object designates, or acts as a means by which to connect to or link to, another object.

11.6.2018

Slide 22 of 42

ELSEVIER

Q SEARCH MENU

Home Journals Journal of Materials Processing Technology



ISSN: 0924-6460

Journal of Materials Processing Technology

Formerly: Journal of Mechanical Working Technology

> Supports Open Access

Editor-in-Chief J. Cao

> View Editorial Board

Submit Your Paper

View Articles


The *Journal of Materials Processing Technology* covers the processing techniques used in manufacturing components from metals and other materials. The journal aims to publish full research papers of original, significant and rigorous work and so to contribute to increased production efficiency and improved...

11.6.2018

Slide 23 of 42

Visegrad Fund

References



uniform on the whole assembly and the used temperature profile is usually linear. It is on the contrary difficult to achieve recommended profile of solder paste manufacturer. Gieczy et al. (2011) demonstrated that this can only be done by sequential dipping of the PCBs into the vapours.

The Golden liquid is a specific product composed of perfluoropolyether substance (PFPE) and the boiling point may be chosen from the range of 55 °C up to 270 °C (Solway, 2014) according to the melting point of the used solder alloy.

According to Prasad (n.d.), the technological disadvantage of the VPS process is the more frequent occurrence of specific defects such as wicking in leaded parts and tombstoning in chip components as Plotog et al. (2008) confirmed. All vapour phase systems can show a difference in component lift due to the fundamental nature of the process. The vapour transfers the heat energy to the surface of the board due to the condensation and phase state change from vapour to liquid. Willis (n.d.) further states that the liquid film may subsequently interact with the components and cause their movement.

1.2 TOMBSTONING

Biocca (2005) refers that tombstoning is one of many common, wetting related defects, arising in electronic manufacturing. A failure having some similarity to tombstoning is billboarding. Unlike tombstoning where a discrete component has one termination

11.6.2018

4 of 42

REFERENCES

Biocca, P., 2005. Lead-free SMT Soldering Defects How to Prevent Them. Glob. SMT Packag. Lead-Free Resour. Guide 11–14.

Choon, T.K., 1996. The origin and prevention of post reflow defects in surface mount assembly. J. Electron. Manuf. 66, 1–12. doi:10.1142/S0960131796000020

Dusek, K., Plasek, M., Benek, D., Dvořáková, K., Radějová, A., 2014. Study of influence of thermal capacity and flux activity on the solderability, in: Proceedings of the 2014 37th International Spring Seminar on Electronics Technology. Presented at the Proceedings of the 2014 37th International Spring Seminar on Electronics Technology, pp. 185–188. doi:10.1109/ISSE.2014.6887589

Dusek, K., Straka, V., Brejcha, M., Beshajova Pelikanova, I., 2013. Influence of type of reflow technology and type of surface finish on tomb-stone effect, in: 2013 36th International Spring Seminar on Electronics Technology (ISSE). Presented at the 2013 36th International Spring Seminar on Electronics Technology (ISSE), pp. 132–135. doi:10.1109/ISSE.2013.6648229


Dusek, K., Urbanek, J., 2008. Surface tension measurement of the solders by non-wetting specimen, in: 31st International Spring Seminar on Electronics Technology, 2008. ISSE '08. Presented at the 31st International Spring Seminar on Electronics Technology, 2008. ISSE '08, pp. 354–357. doi:10.1109/ISSE.2008.5276667

Dusek, K., Urbanek, J., 2006. Influence of the reduced oxygen concentration on the wetting force, in: 2006 29th International Spring Seminar on Electronics Technology. Presented at the 2006 29th International Spring Seminar on Electronics Technology, pp. 193–196. doi:10.1109/ISSE.2006.365384

Frear, D.R., Burchett, S.N., Morgan, H.S., Lau, J.H., 1994. Physical Metallurgy of solder-substrate reactions, in: Mechanics of Solder Alloy Interconnects. Springer Science & Business Media.

Gicry, A., Illis, B., Damai, T., 2015a. Investigating condensation heat transfer during vapor phase soldering on round-shaped PCB plates. Int. J. Heat Mass Transf. 86, 639–647. doi:10.1016/j.jheatmasstransfer.2015.02.068

11.6.2018



VIA
ViaGroup Network
www.via-group.com

Slide 25 of 42



Home > Journals > Microelectronics Reliability

Microelectronics Reliability

Supports Open Access

Editor-in-Chief: Dr. M. Tahoori

View Editorial Board

ISSN: 0026-2714

Submit Your Paper

View Articles

Guide for Authors

Read more

Most Downloaded Recent Articles Most Cited Open Access Articles

11.6.2018



Microelectronics Reliability

Microelectronics Reliability, is dedicated to disseminating the latest research results and related information on the reliability of microelectronic devices, circuits and systems, from materials, process and manufacturing, to design, testing and operation. The coverage of the journal includes the following...

Slide 26 of 42

for macrovoid was set out to 100 µm. Macrovoids are considered as process-dependent-voids as they originate during the manufacturing process. The factors that have impact on voids are shown in Fishbone diagram, see Fig. 2.

1.4. Soldering process, void formation

Volatile compounds from the paste are evaporated and the solder paste melts during the soldering process. The evaporation takes place throughout the volume of the paste, not just on the surface. Gaseous components tend to leave the molten solder alloy but some of them remain trapped inside and create voids. The void formation principle is depicted in Fig. 3.

At first, solvents start evaporating due to temperature elevation. The solder paste is then heated to a temperature in which the flux is activated. The flux subsequently removes oxides from the surfaces to be joined and from the solder particles. The more oxides exist on the metallization and solder particles, the longer the outgassing takes and the more voids will remain entrapped in the joint at the end. Therefore it is necessary to give the flux enough time to remove the oxides. The outgassing may come not just as a result of oxides reduction but also as a result of evaporation of moisture or process chemicals trapped within PCB.

The use of inert atmosphere changes the surface tension of the molten solder [11] and therefore the ability of the cavity to leave through the surface of the molten alloy is influenced. The lead-free solder alloys have higher surface tension in comparison to tin-lead solders [12–14], therefore the cavities do not leave the molten joint easily and the probability of voids occurrence is higher.

11.6.2018

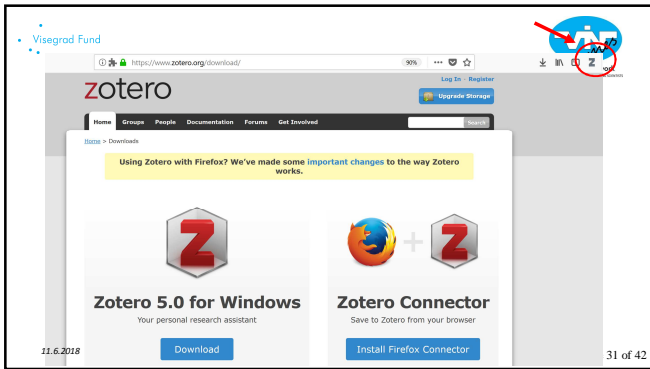
used as a reflow parameter for solder pastes. The heating factor is from the perspective of reliability an ideal parameter for reflow profile optimization [15]. Study carried out by Hirman et al. [16] states that heating factor influences the intermetallic thickness. According to studies [17,18] there is no need to pay particular attention to the shape of a reflow profile if the heating factor is according to recommendation and dwell time, reflow peak temperature change and other parameters are within a usual range.

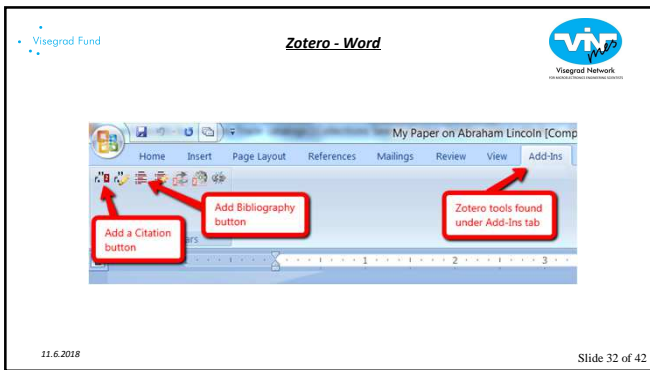
1.5. Reliability concerns and voiding

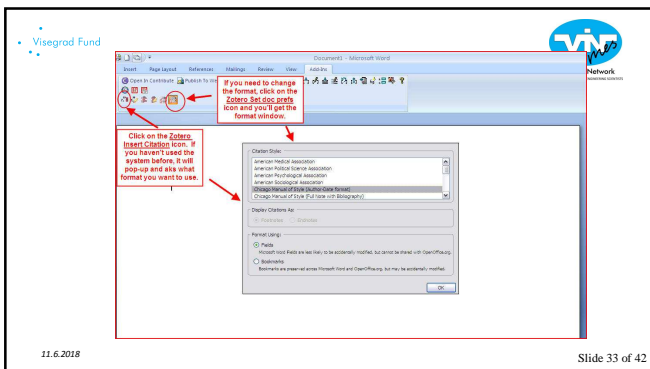
Most studies on joint-void topic are dealing with the voids as a soldering reliability problem. The Kirkendall voids cause according to a study by Goyal, D. et al. [19] an increase in brittleness of the joint. M. Yunus et al. [20] conclude that large voids, irrespectively of their location, significantly reduce joint life and crack propagation is accelerated with the presence of small voids on component side. Chiu, T. C. et al. [21] proved that there is a very strong correlation between drop reliability and voiding. Previti, M.A. et al. [22] and several other studies [23–25] are therefore focused on minimizing the void presence.

Contrary, opinions from soldering companies [26,27] are that small and uniformly dispersed macrovoids are a necessary and required component of the joint. The issue as to whether and how voids affect the reliability of solder joints is still under discussion, voids may act as stress relievers and crack arresters; equally they can be stress raisers. They can be located anywhere in the soldered joint volume and their location has higher influence on the reliability than their size [9]. Macrovoids, uniformly dispersed in the joint volume may increase the reliability of the joint, but their presence on the material boundary is always undesirable as the probability of the mechanical disintegration is increased.

12







Google Scholar search results for "current density and temperature". The search bar shows the query. The results list several papers, including "Three-dimensional finite element analysis of current density and temperature distributions during radio-frequency ablation" and "Very low threshold current density room temperature continuous-wave lasing from a single-layer InAs quantum-dot laser". A red arrow points to the "Save to Zotero (Zotero Connector)" button in the top right corner.

Slide 34 of 42

Google Scholar search results for "current density and temperature". A Zotero Connector overlay is visible, showing a list of items to be added to the library. The items include "Three-dimensional finite element analysis of current density and temperature distributions during radio-frequency ablation" and "Very low threshold current density room temperature continuous-wave lasing from a single-layer InAs quantum-dot laser". The overlay also shows a "Select All" button and a "Cancel" button.

Slide 35 of 42

Slide titled "Single citation - „one by one“". The slide features the Visegrad Fund logo and the Visegrad Network logo. It displays a list of citations, including "Influence of high solder joint detachment: cause, warning effect" and "The effect of void quantity and size in soldered joints". A red box highlights the "Cite" button in the citation list.

Slide 36 of 42

Visegrad Fund

Multiple citations

Visegrad Network

Document1 - Word

Subotai Dondi Wiktor Marki Reuben Reference Correspondence Reize Zdzisław Zdzisł Dopily ABBYY FineReader 11

Visegrad priority ratings

HERE

[1] 'Are Voids in Solder Joints Really an Issue?' | EPTAC...
 [2] M. A. Previti, M. Holtzer, and T. Hunsinger, 'Four ways to reduce voids in BGA/CSP Package to substrate connections', in *SMTA International Conference Proceedings*, Gurnee Associates, Orlando, FL, 2010, pp. 655-662.
 [3] Z. Balfes, Y. K. Tai, Y. L. Tsai, and R. Dauter, 'How to improve void performance in water bumping', in *Electronics Packaging Technology Conference (EPTC)*, 2014 IEEE 16th, 2014, pp. 743-746.

11.6.2018 Slide 40 of 42

Visegrad Fund

Download reference style for selected journal

Visegrad Network

- <https://www.zotero.org/styles>

Zotero Style Repository

Here you can find [Citation Style Language](#) 1.0.1 citation styles for use with [Zotero](#) and other CSL 1.0.1-compatible software. For more information on using CSL styles with Zotero, see the [Zotero wiki](#).

Style Search **Format:** numeric

Fields:

4 styles found:


- [Journal of Materials Science](#) (2014-05-18 01:40:33)
- [Journal of Materials Science & Technology](#) (2008-03-09 03:06:46)
- [Journal of Materials Science: Materials in Electronics](#) (2014-05-18 01:40:33)
- [Journal of Materials Science: Materials in Medicine](#) (2014-05-18 01:40:33)

11.6.2018 Slide 41 of 42


Visegrad Fund

Visegrad Network

11.6.2018 Slide 42 of 42

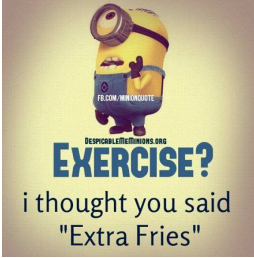


Visegrad Fund



Vinograd Network

Zotero - exercise



DESPICABLEMINIONS.ORG

EXERCISE?

i thought you said
"Extra Fries"

11.6.2018

Slide 43 of 42
